



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

|                                                                                                                                                                                |                      |                                            |                   |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------|--------------------------------------------|-------------------|
| <b>PCN Number:</b>                                                                                                                                                             | <b>20260827000.1</b> | <b>PCN Issued</b>                          | August 27, 2026   |
| Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet update and TI Chengdu (CDAT) as an additional Assembly site and BOM options for select devices |                      | <b>Sample request deadline:</b>            | October 26, 2026  |
|                                                                                                                                                                                |                      | <b>Estimated 1<sup>st</sup> ship date:</b> | November 25, 2026 |
| <b>*Sample requests received after October 26, 2026* will not be supported.</b>                                                                                                |                      |                                            |                   |

#### Change type(s)

Assembly Site  
Assembly Process  
Assembly Material  
Packing/Shipping/Labeling  
Design  
Data Sheet/Electrical Specification  
Wafer Fab Site  
Wafer Fab Material  
Wafer Fab Process

#### PCN Details

#### Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab & process technology (RFAB, LBC9), TI Chengdu (CDAT) as assembly site option and BOM options for select devices as listed below in the product affected section.

| Current Fab Site |           |                | Additional Fab Site |         |                |
|------------------|-----------|----------------|---------------------|---------|----------------|
| Current Fab Site | Process   | Wafer Diameter | Additional Fab Site | Process | Wafer Diameter |
| FFAB             | ASLNONC10 | 200mm          | RFAB                | LBC9    | 300mm          |

The die was also changed as a result of the process change.

Construction Differences are as follows:

|                      | Current  | Current    | Additional |
|----------------------|----------|------------|------------|
| Assembly & Test site | MLA      | CRS        | CDAT       |
| Wire bond diam/type  | Cu, 0.96 | Cu, 1.0    | Cu, 0.8    |
| Leadfinish           | NiPdAu   | NiPdAu     | Matte Sn   |
| Mount compound       | 4205846  | SID#435143 | 4207123    |
| Mold compound        | 4208625  | SID#435370 | 4222198    |
| MSL Level            | MSL 2    | MSL 2      | MSL 1      |

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history shown below. The links to the revised datasheets are available in the table below.

**Changes from Revision A (March 2005) to Revision B (August 2026)**
**Page**

|                                                                                                              |   |
|--------------------------------------------------------------------------------------------------------------|---|
| • Updated the numbering format for tables, figures, and cross-references throughout the document.....        | 1 |
| • Removed Ordering Information table .....                                                                   | 4 |
| • Added the <i>ESD Ratings</i> table.....                                                                    | 5 |
| • Added the <i>Thermal Information</i> table.....                                                            | 6 |
| • Updated $I_{CCD}$ values in the <i>Electrical Characteristics</i> table. ....                              | 7 |
| • Updated the $t_{pd}$ , $t_{en}$ , and $t_{dis}$ values in the <i>Switching Characteristics</i> table ..... | 7 |
| • Added the latest typical curve data to the <i>Typical Characteristics</i> section.....                     | 9 |

**Changes from Revision C (June 2018) to Revision D (August 2026)**
**Page**

|                                                                                                                               |   |
|-------------------------------------------------------------------------------------------------------------------------------|---|
| • Updated the numbering format for tables, figures, and cross-references throughout the document.....                         | 1 |
| • Added the DYY package to the document.....                                                                                  | 1 |
| • Added operating free-air temperature minimum and maximum values in the <i>Recommended Operating Conditions</i> table.....   | 4 |
| • Updated all values in the <i>Thermal Information</i> table .....                                                            | 5 |
| • Added the DYY package to the <i>Thermal Information</i> table .....                                                         | 5 |
| • Changed the typical $I_{CCD}$ per input control value in the <i>Electrical Characteristics</i> table from 0.04 to 0.23..... | 5 |
| • Changed the maximum $I_{CCD}$ per input control value in the <i>Electrical Characteristics</i> table from 0.05 to 0.25...   | 5 |
| • Added the <i>Electrical Characteristics: DYY Package</i> table.....                                                         | 6 |
| • Added the <i>Switching Characteristics: DYY Package</i> table.....                                                          | 7 |
| • Added the latest typical curve data to the <i>Typical Characteristics</i> section.....                                      | 8 |

**Changes from Revision B (March 2005) to Revision C (August 2026)**
**Page**

|                                                                                                                               |   |
|-------------------------------------------------------------------------------------------------------------------------------|---|
| • Deleted the GQN package from the document.....                                                                              | 1 |
| • Updated the number formatting for tables, figures, and cross-references throughout the document .....                       | 1 |
| • Removed Ordering Information table. ....                                                                                    | 1 |
| • Added the <i>ESD Ratings</i> table.....                                                                                     | 3 |
| • Added the <i>Thermal Information</i> table and moved $R_{\theta JA}$ values to the table.....                               | 4 |
| • Updated the maximum <i>Per input control</i> parameter in the <i>Electrical Characteristics</i> table from 0.35 to 0.45.... | 4 |
| • Updated the maximum $V_{CC}$ rating for $t_{en}$ and $t_{dis}$ in the <i>Switching Characteristics</i> table.....           | 5 |

**Changes from Revision B (March 2005) to Revision C (August 2026)**
**Page**

|                                                                                                                                                                                                                                                                  |   |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---|
| • Updated the numbering format for tables, figures, and cross-references throughout the document.....                                                                                                                                                            | 1 |
| • Added <i>Device Information</i> table, <i>ESD Ratings</i> table, <i>Device Functional Modes</i> , <i>Typical Characteristics</i> , <i>Device and Documentation Support</i> sections, and <i>Mechanical, Packaging, and Orderable Information</i> section. .... | 1 |
| • Changed pin 16 from: B9 to: B3 in the RGY package.....                                                                                                                                                                                                         | 4 |
| • Removed the Ordering Information table.....                                                                                                                                                                                                                    | 4 |
| • Added the <i>Thermal Information</i> table.....                                                                                                                                                                                                                | 6 |
| • Updated the $C_{in}$ values in the <i>Electrical Characteristics</i> table.....                                                                                                                                                                                | 6 |
| • Updated the $t_{en}$ and $t_{dis}$ values in the <i>Switching Characteristics</i> table.....                                                                                                                                                                   | 7 |

| Changes from Revision E (December 2024) to Revision F (August 2026)                                                                                                   | Page |
|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|
| • Updated the number formatting for tables, figures, and cross-references throughout the document .....                                                               | 1    |
| • Updated the <i>Thermal Information</i> table values .....                                                                                                           | 5    |
| • Updated the maximum value of the <i>Per input control</i> parameter in the <i>Electrical Characteristics - PKG = RGY, PW, DBQ, DGV</i> table from 0.35 to 0.45..... | 5    |
| • Updated new package information to the <i>Switching Characteristics</i> tables .....                                                                                | 7    |
| • Updated the <i>Typical Characteristics</i> section.....                                                                                                             | 8    |



SN74CB3Q3244

SCDS154C – OCTOBER 2003 – REVISED AUGUST 2026

| Changes from Revision B (December 2004) to Revision C (August 2026)                                                          | Page |
|------------------------------------------------------------------------------------------------------------------------------|------|
| • Updated the numbering format for tables, figures, and cross-references throughout the document .....                       | 1    |
| • Deleted the <i>Ordering Information</i> table from the document.....                                                       | 1    |
| • Deleted the GQN package from the document.....                                                                             | 4    |
| • Added the <i>ESD Ratings</i> table.....                                                                                    | 5    |
| • Added the <i>Thermal Information</i> table and moved $R_{\theta JA}$ to the table.....                                     | 6    |
| • Changed the typical $I_{CCD}$ per input control value in the <i>Electrical Characteristics</i> table from 0.14 to 0.3..... | 7    |
| • Changed the maximum $I_{CCD}$ per input control value in the <i>Electrical Characteristics</i> table from 0.15 to 0.45...  | 7    |
| • Updated the maximum $V_{CC}$ values for $t_{dis}$ in the <i>Switching Characteristics</i> table.....                       | 7    |
| • Added the latest typical curve data to the <i>Typical Characteristics</i> section.....                                     | 8    |

| Product Folder | Current Datasheet Number | New Datasheet Number | Link to full datasheet                                                                        |
|----------------|--------------------------|----------------------|-----------------------------------------------------------------------------------------------|
| SN74CB3Q3251   | SCDS173A                 | SCDS173B             | <a href="https://www.ti.com/product/SN74CB3Q3251">https://www.ti.com/product/SN74CB3Q3251</a> |
| SN74CB3Q3253   | SCDS145C                 | SCDS145D             | <a href="https://www.ti.com/product/SN74CB3Q3253">https://www.ti.com/product/SN74CB3Q3253</a> |
| SN74CB3Q3245   | SCDS124B                 | SCDS124C             | <a href="https://www.ti.com/product/SN74CB3Q3245">https://www.ti.com/product/SN74CB3Q3245</a> |
| SN74CB3Q3345   | SCDS144B                 | SCDS144C             | <a href="https://www.ti.com/product/SN74CB3Q3345">https://www.ti.com/product/SN74CB3Q3345</a> |
| SN74CB3Q3257   | SCDS135E                 | SCDS135F             | <a href="https://www.ti.com/product/SN74CB3Q3257">https://www.ti.com/product/SN74CB3Q3257</a> |
| SN74CB3Q3244   | SCDS154B                 | SCDS154C             | <a href="https://www.ti.com/product/SN74CB3Q3244">https://www.ti.com/product/SN74CB3Q3244</a> |

Qual details are provided in the Qual Data Section.

**Reason for Change:** Continuity of supply

| <b>Anticipated impact on Form, Fit, Function, Quality or Reliability:</b> | <ul style="list-style-type: none"><li>Physical aspects of the device have changed</li><li>Device quality has improved</li><li>Request the Supporting Data Packet and review updated Datasheets for more details on the changes. Evaluating samples is encouraged.</li></ul>                                                                                                                                                                                                                                                      |                                               |                                               |              |           |                                               |                                               |                                               |                                               |
|---------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|-----------------------------------------------|--------------|-----------|-----------------------------------------------|-----------------------------------------------|-----------------------------------------------|-----------------------------------------------|
| <b>Impact on Environmental Ratings</b>                                    | <p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table><tr><th>RoHS</th><th>REACH</th><th>Green Status</th><th>IEC 62474</th></tr><tr><td><input checked="" type="checkbox"/> No Change</td><td><input checked="" type="checkbox"/> No Change</td><td><input checked="" type="checkbox"/> No Change</td><td><input checked="" type="checkbox"/> No Change</td></tr></table> | RoHS                                          | REACH                                         | Green Status | IEC 62474 | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |
| RoHS                                                                      | REACH                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            | Green Status                                  | IEC 62474                                     |              |           |                                               |                                               |                                               |                                               |
| <input checked="" type="checkbox"/> No Change                             | <input checked="" type="checkbox"/> No Change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    | <input checked="" type="checkbox"/> No Change | <input checked="" type="checkbox"/> No Change |              |           |                                               |                                               |                                               |                                               |
| <b>Changes to product identification resulting from</b>                   | <table><tr><th colspan="4">Fab Site Information</th></tr><tr><td>Chip Site</td><td>Chip Site</td><td>Chip Site</td><td>Chip Site City</td></tr></table>                                                                                                                                                                                                                                                                                                                                                                          | Fab Site Information                          |                                               |              |           | Chip Site                                     | Chip Site                                     | Chip Site                                     | Chip Site City                                |
| Fab Site Information                                                      |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |                                               |                                               |              |           |                                               |                                               |                                               |                                               |
| Chip Site                                                                 | Chip Site                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                        | Chip Site                                     | Chip Site City                                |              |           |                                               |                                               |                                               |                                               |

this PCN:

|             |                      |                          |                   |
|-------------|----------------------|--------------------------|-------------------|
|             | Origin Code<br>(20L) | Country<br>Code<br>(21L) |                   |
| FFAB        | TID                  | DEU                      | Freising          |
| <b>RFAB</b> | <b>RFB</b>           | <b>USA</b>               | <b>Richardson</b> |

Die Rev:

Current

New

|              |                     |
|--------------|---------------------|
| Die Rev [2P] | <b>Die Rev [2P]</b> |
| A            | -                   |

Assembly Site

Information

|                       |                                  |                                   |                |
|-----------------------|----------------------------------|-----------------------------------|----------------|
| Assembly<br>Site      | Assembly<br>Site Origin<br>(22L) | Assembly<br>Country<br>Code (23L) | Assembly City  |
| Carsem                | CRS                              | MY                                | Jelapang, Ipoh |
| TI Malaysia           | MLA                              | MYS                               | Kuala Lumpur   |
| <b>TI<br/>Chengdu</b> | <b>CDA</b>                       | <b>CHN</b>                        | <b>Chengdu</b> |

Sample product shipping label (not actual product label):

| Products Affected: |                  |                  |  |
|--------------------|------------------|------------------|--|
| SN74CB3Q3244RGYR   | SN74CB3Q3245RGYR | SN74CB3Q3251RGYR |  |
| SN74CB3Q3257RGYR   | SN74CB3Q3345RGYR | SN74CB3Q3253RGYR |  |

Texas Instruments Incorporated

TI Information - Selective Disclosure

PCN: 20260827000.1

**Qualification Report**  
**Redbull MUX2.0\_Wave4B Part 2/5 CDAT**  
**Approve Date 04-June-2026**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Type  | #  | Test Name                           | Condition                                                                            | Duration      | Qual Device:<br>SN74CB3Q3251RGYR | Qual Device:<br>SN74CB3Q3253RGYR | Qual Device:<br>SN74CB3Q3244RGYR | QBS Process<br>Reference:<br>TLV62568DBVR | QBS Process<br>Reference:<br>XM0C1104QRUKRQ1 | QBS Package<br>Reference:<br>BQ402552RSMR | QBS Product<br>Reference:<br>SN74CB3Q3245RGYR |
|-------|----|-------------------------------------|--------------------------------------------------------------------------------------|---------------|----------------------------------|----------------------------------|----------------------------------|-------------------------------------------|----------------------------------------------|-------------------------------------------|-----------------------------------------------|
| HAST  | A2 | Biased HAST                         | 130C/85%RH                                                                           | 96<br>Hours   | -                                | -                                | -                                | -                                         | 3/231/0                                      | -                                         | -                                             |
| UHAST | A3 | Unbiased HAST                       | 130C/85%RH                                                                           | 96<br>Hours   | -                                | -                                | -                                | -                                         | 3/231/0                                      | 3/231/0                                   | -                                             |
| TC    | A4 | Temperature<br>Cycle                | -65C/150C                                                                            | 500<br>Cycles | -                                | -                                | -                                | -                                         | 3/231/0                                      | 3/231/0                                   | -                                             |
| HTSL  | A6 | High<br>Temperature<br>Storage Life | 150C                                                                                 | 1000<br>Hours | -                                | -                                | -                                | -                                         | 3/135/0                                      | 3/231/0                                   | -                                             |
| HTOL  | B1 | Life Test                           | 150C                                                                                 | 300<br>Hours  | -                                | -                                | -                                | 3/231/0                                   | -                                            | -                                         | -                                             |
| ELFR  | B2 | Early Life<br>Failure Rate          | 125C                                                                                 | 48<br>Hours   | -                                | -                                | -                                | 3/3000/0                                  | -                                            | -                                         | -                                             |
| SD    | C3 | PB-Free<br>Solderability            | Precondition<br>w/155C Dry<br>Bake (4 hrs<br>+/- 15<br>minutes); PB-<br>Free Solder; | -             | -                                | -                                | -                                | -                                         | 1/15/0                                       | 1/22/0                                    | -                                             |
| PD    | C4 | Physical<br>Dimensions              | Cpk>1.67                                                                             | -             | -                                | -                                | -                                | -                                         | 3/30/0                                       | -                                         | -                                             |
| ESD   | E2 | ESD CDM                             | -                                                                                    | 1000<br>Volts | 1/3/0                            | 1/3/0                            | 1/3/0                            | -                                         | -                                            | -                                         | 1/3/0                                         |
| ESD   | E2 | ESD HBM                             | -                                                                                    | 2000<br>Volts | 1/3/0                            | 1/3/0                            | 1/3/0                            | -                                         | -                                            | -                                         | 1/3/0                                         |
| LU    | E4 | Latch-Up                            | Per JESD78                                                                           | -             | 1/3/0                            | 1/3/0                            | 1/3/0                            | -                                         | -                                            | -                                         | 1/3/0                                         |
| CHAR  | E5 | Electrical<br>Characterization      | Min, Typ, Max<br>Temp                                                                | -             | 1/30/0                           | 1/30/0                           | 1/30/0                           | -                                         | -                                            | -                                         | 1/30/0                                        |
| CHAR  | E5 | Electrical<br>Characterization      | Per<br>Datasheet<br>Parameters                                                       | -             | 1/30/0                           | 1/30/0                           | 1/30/0                           | -                                         | -                                            | -                                         | 1/30/0                                        |

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3345RGYR is qualified at MSL1 260C
- Qual Device SN74CB3Q3251RGYR is qualified at MSL1 260C
- Qual Device SN74CB3Q3253RGYR is qualified at MSL1 260C
- Qual Device SN74CB3Q3244RGYR is qualified at MSL1 260C
- Qual Device SN74CB3Q3257RGYR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
TI Qualification ID: R-CHG-2409-021

**Qualification Report**  
**Approve Date 09-December-2025**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

| Type  | #  | Test Name                     | Condition                                                            | Duration   | Qual Device:<br><a href="#">SN74CB3Q3245RGYR</a> | QBS<br>Reference:<br><a href="#">TLV62568DBVR</a> | QBS Reference:<br><a href="#">XM0C1104QRUKRQ1</a> | QBS Reference:<br><a href="#">BQ40Z552RSMR</a> |
|-------|----|-------------------------------|----------------------------------------------------------------------|------------|--------------------------------------------------|---------------------------------------------------|---------------------------------------------------|------------------------------------------------|
| HAST  | A2 | Biased HAST                   | 130C/85%RH                                                           | 96 Hours   | -                                                | -                                                 | 3/231/0                                           | -                                              |
| UHAST | A3 | Unbiased HAST                 | 130C/85%RH                                                           | 96 Hours   | -                                                | -                                                 | 3/231/0                                           | 3/231/0                                        |
| TC    | A4 | Temperature Cycle             | -65C/150C                                                            | 500 Cycles | -                                                | -                                                 | 3/231/0                                           | 3/231/0                                        |
| HTSL  | A6 | High Temperature Storage Life | 150C                                                                 | 1000 Hours | -                                                | -                                                 | 3/135/0                                           | 3/231/0                                        |
| HTOL  | B1 | Life Test                     | 150C                                                                 | 300 Hours  | -                                                | 3/231/0                                           | -                                                 | -                                              |
| ELFR  | B2 | Early Life Failure Rate       | 125C                                                                 | 48 Hours   | -                                                | 3/3000/0                                          | -                                                 | -                                              |
| SD    | C3 | PB-Free Solderability         | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)                  | -          | -                                                | -                                                 | 1/15/0                                            | -                                              |
| SD    | C3 | PB-Free Solderability         | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder; | -          | -                                                | -                                                 | -                                                 | 1/22/0                                         |
| PD    | C4 | Physical Dimensions           | Cpk>1.67                                                             | -          | -                                                | -                                                 | 3/30/0                                            | -                                              |
| ESD   | E2 | ESD CDM                       | -                                                                    | 1000 Volts | 1/3/0                                            | -                                                 | -                                                 | -                                              |

| Type | #  | Test Name                   | Condition                | Duration   | Qual Device:<br><a href="#">SN74CB3Q3245RGYR</a> | QBS<br>Reference:<br><a href="#">TLV62568DBVR</a> | QBS Reference:<br><a href="#">XM0C1104QRUKRQ1</a> | QBS Reference:<br><a href="#">BQ40Z552RSMR</a> |
|------|----|-----------------------------|--------------------------|------------|--------------------------------------------------|---------------------------------------------------|---------------------------------------------------|------------------------------------------------|
| ESD  | E2 | ESD HBM                     | -                        | 2000 Volts | 1/3/0                                            | -                                                 | 1/3/0                                             | -                                              |
| LU   | E4 | Latch-Up                    | Per JESD78               | -          | 1/3/0                                            | -                                                 | 1/3/0                                             | -                                              |
| CHAR | E5 | Electrical Characterization | Min, Typ, Max Temp       | -          | 1/30/0                                           | -                                                 | -                                                 | -                                              |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | -          | 1/30/0                                           | -                                                 | -                                                 | -                                              |

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74CB3Q3245RGYR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2508-030

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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